

ABS SILICON BRIDGE RECTIFIERV

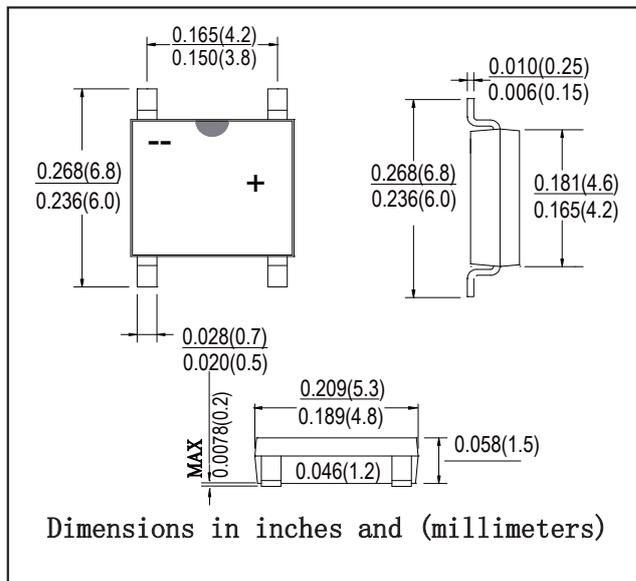
REVERSE VOLTAGE: 200 --- 1000V CURRENT: 0.8A

FEATURES

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0

MECHANICAL DATA

- Case: ABS molded plastic
- Terminals: plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting position: Any
- Marking: type number



MAXIMUM RATINGS AND CHARACTERISTICS

@ 25°C Ambient Temperature (unless otherwise noted)

TYPE NUMBER	SYMBOL	ABS2	ABS4	ABS6	ABS8	ABS10	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM}						
	V_{RWM}	200	400	600	800	1000	V
	V_{DC}						
RMS Reverse Voltage	V_{RMS}	140	280	420	560	700	V
Average Rectified Output Current (Note 1) @ $T_A=30^\circ\text{C}$ (Note 2) @ $T_A=30^\circ\text{C}$	I_o			0.5 0.8			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}			30			A
Forward Voltage per element @ $I_F=0.4\text{A}$	V_{FM}			0.95			V
Peak Reverse Current @ $T_A=25^\circ\text{C}$ At Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	I_R			5.0 500			μA
Typical Thermal Resistance per leg (Note 3)	$R_{\theta JA}$			62.5			$^\circ\text{C/W}$
	$R_{\theta JL}$			25			
Operating and Storage Temperature Range	T_J, T_{STG}			-55to+150			$^\circ\text{C}$

- Note: 1. Mounted on glass epoxy PC board with 1.3mm² solder pad.
 2. Mounted on aluminum substrate PC board with 1.3mm² solder pad.
 3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

RATINGS AND CHARACTERISTIC CURVES

FIG.1 MAXIMUM FORWARD CURRENT DERATING CURVE

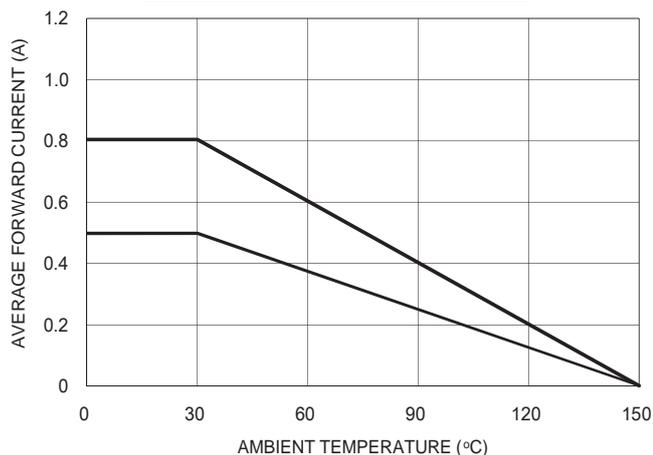


FIG. 2 TYPICAL FORWARD CHARACTERISTIC

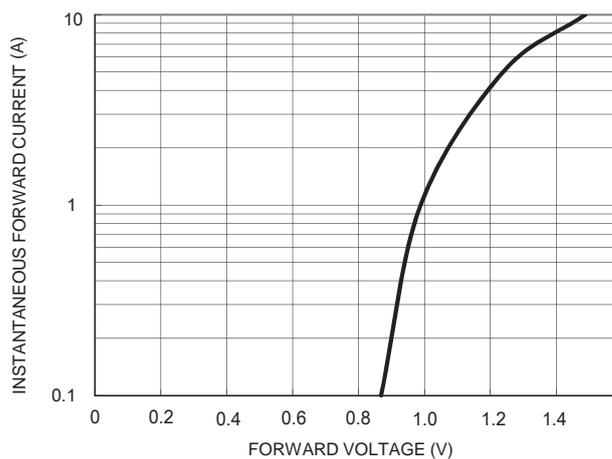


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

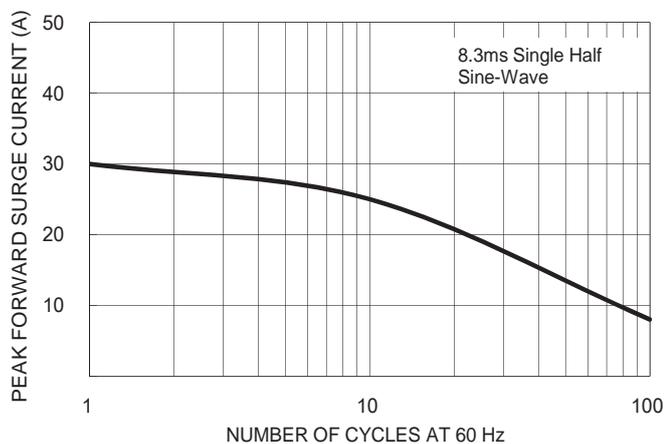


FIG. 4 TYPICAL REVERSE CHARACTERISTICS

